

SOT597-1

plastic thin fine-pitch ball grid array package; 96 balls; body
8 x 8 x 0.8 mm

8 February 2016

Package information

1. Package summary

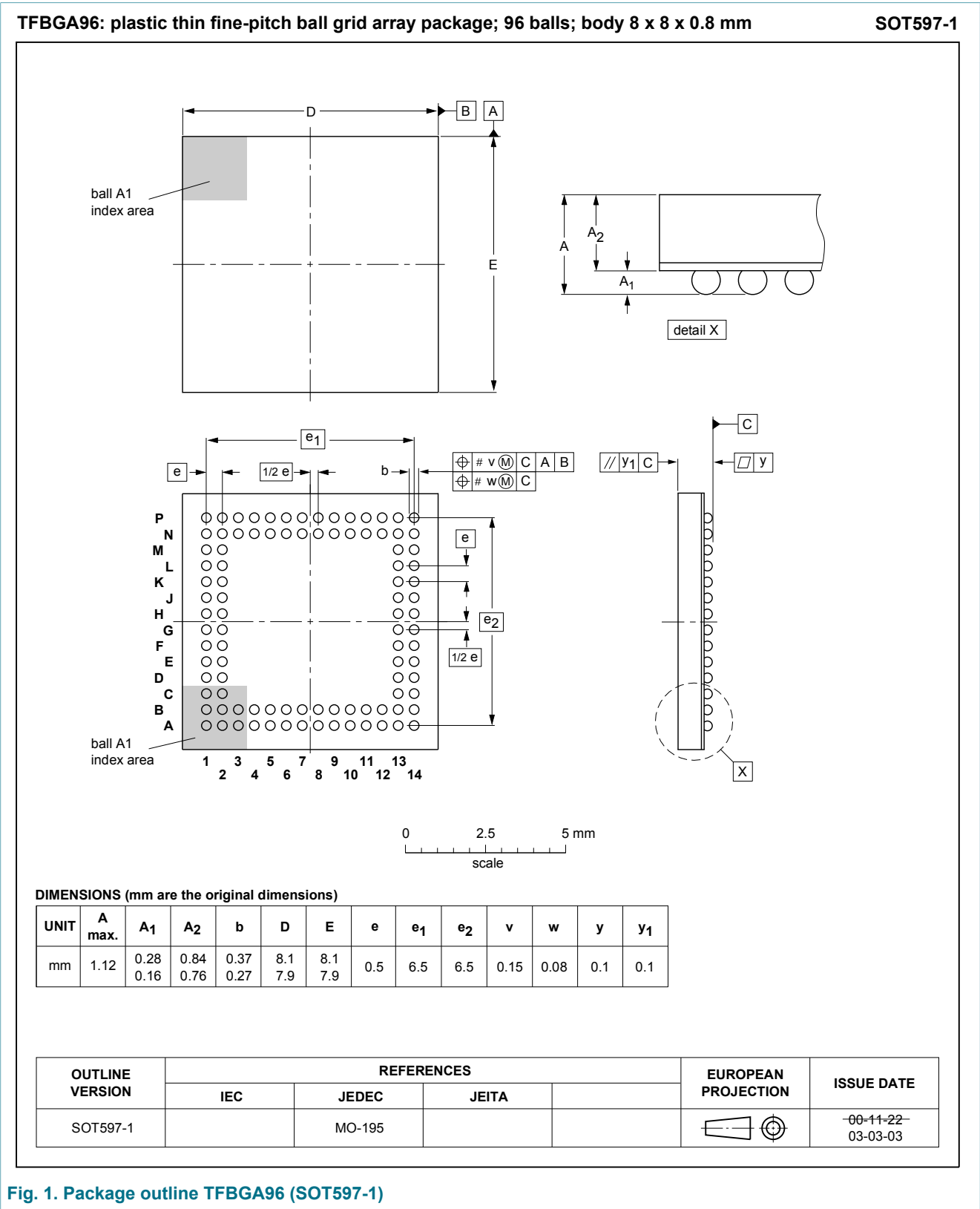
Terminal position code	B (bottom)
Package type descriptive code	TFBGA96
Package type industry code	TFBGA96
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	3-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		7.9	-	8	8.1	mm
E	package width		7.9	-	8	8.1	mm
A	seated height		[tbd]	-	1.12	1.12	mm
A ₂	package height		0.76	-	0.8	0.84	mm
n ₂	actual quantity of termination		-	-	96	-	



2. Package outline



3. Soldering

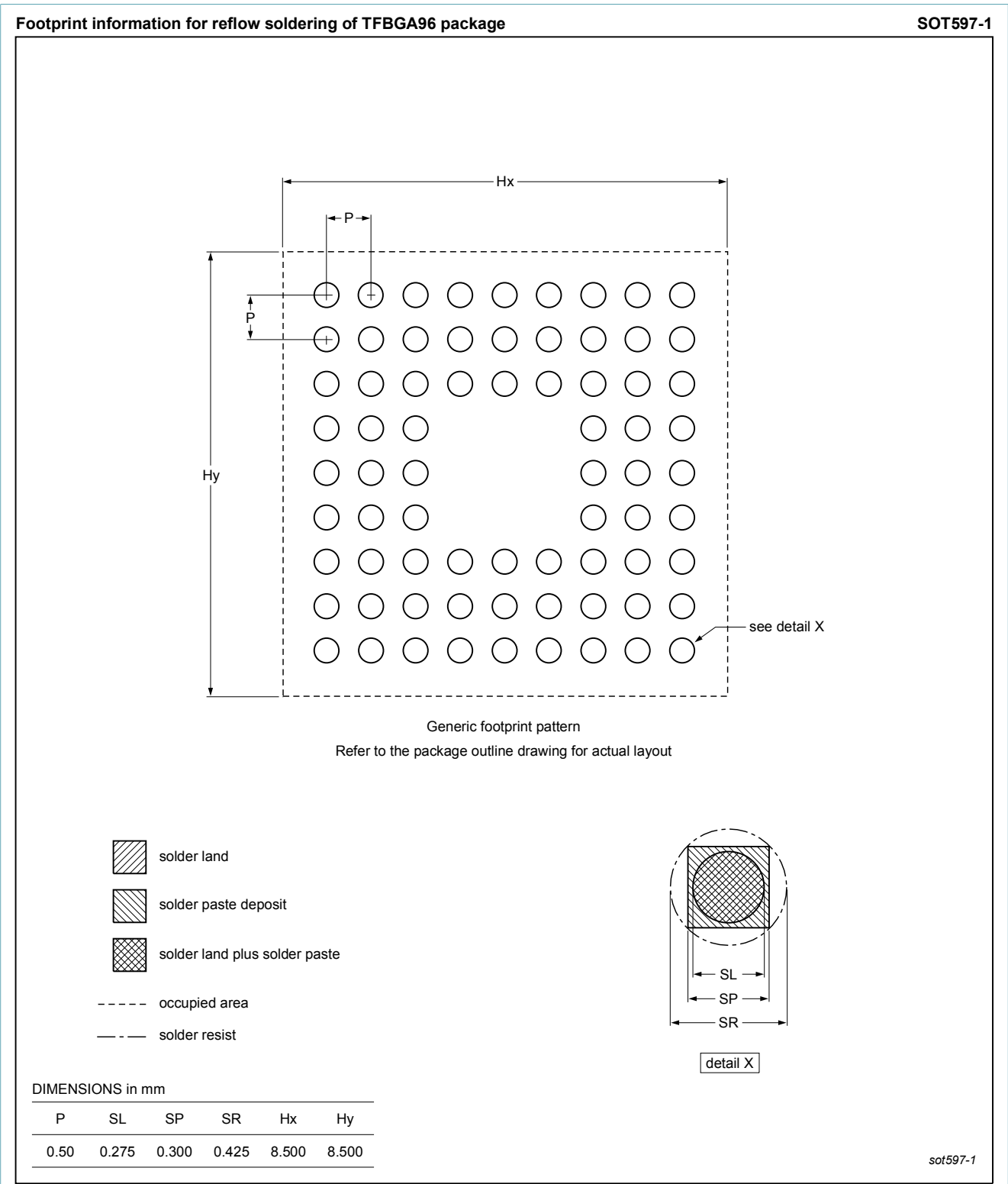


Fig. 2. Reflow soldering footprint for TFBGA96 (SOT597-1)

4. Legal information

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